

August 1984 Revised May 1999

# MM74HC4051 • MM74HC4052 • MM74HC4053 8-Channel Analog Multiplexer • Dual 4-Channel Analog Multiplexer • Triple 2-Channel Analog Multiplexer

## **General Description**

The MM74HC4051, MM74HC4052 and MM74HC4053 multiplexers are digitally controlled analog switches implemented in advanced silicon-gate CMOS technology. These switches have low "on" resistance and low "off" leakages. They are bidirectional switches, thus any analog input may be used as an output and vice-versa. Also these switches contain linearization circuitry which lowers the on resistance and increases switch linearity. These devices allow control of up to ±6V (peak) analog signals with digital control signals of 0 to 6V. Three supply pins are provided for  $V_{CC}$ , ground, and  $V_{EE}$ . This enables the connection of 0-5V logic signals when  $V_{\mbox{\footnotesize{CC}}} = 5V$  and an analog input range of  $\pm 5V$  when  $V_{FF} = 5V$ . All three devices also have an inhibit control which when HIGH will disable all switches to their off state. All analog inputs and outputs and digital inputs are protected from electrostatic damage by diodes to  $\ensuremath{V_{CC}}$  and ground.

MM74HC4051: This device connects together the outputs of 8 switches, thus achieving an 8 channel Multiplexer. The binary code placed on the A, B, and C select lines determines which one of the eight switches is "on", and connects one of the eight inputs to the common output.

MM74HC4052: This device connects together the outputs of 4 switches in two sets, thus achieving a pair of 4-channel multiplexers. The binary code placed on the A, and B select lines determine which switch in each 4 channel section is "on", connecting one of the four inputs in each section to its common output. This enables the implementation of a 4-channel differential multiplexer.

MM74HC4053: This device contains 6 switches whose outputs are connected together in pairs, thus implementing a triple 2 channel multiplexer, or the equivalent of 3 single-pole-double throw configurations. Each of the A, B, or C select lines independently controls one pair of switches, selecting one of the two switches to be "on".

### **Features**

- Wide analog input voltage range: ±6V
- Low "on" resistance: 50 typ. (V<sub>CC</sub>-V<sub>EE</sub> = 4.5V)
  - 30 typ.  $(V_{CC}-V_{EE} = 9V)$
- Logic level translation to enable 5V logic with ±5V analog signals
- Low quiescent current: 80 µA maximum (74HC)
- Matched Switch characteristic

## **Ordering Code:**

Order Number	Package Number	Package Description
MM74HC4051M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC4051WM	M16B	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC4051SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC4051MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC4051N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-0010.300" Wide
MM74HC4052M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC4052WM	M16B	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC4052SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC4052MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC4052N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-0010.300" Wide
MM74HC4053M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC4053WM	M16B	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC4053SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC4053MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC4053N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-0010.300" Wide

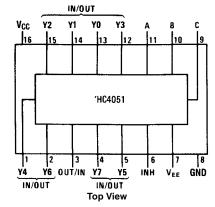
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

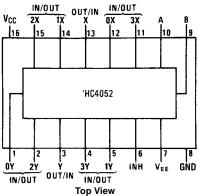
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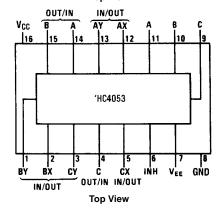
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# **Connection Diagrams**

Pin Assignments for DIP, SOIC, SOP and TSSOP







## **Truth Tables**

### MM744051

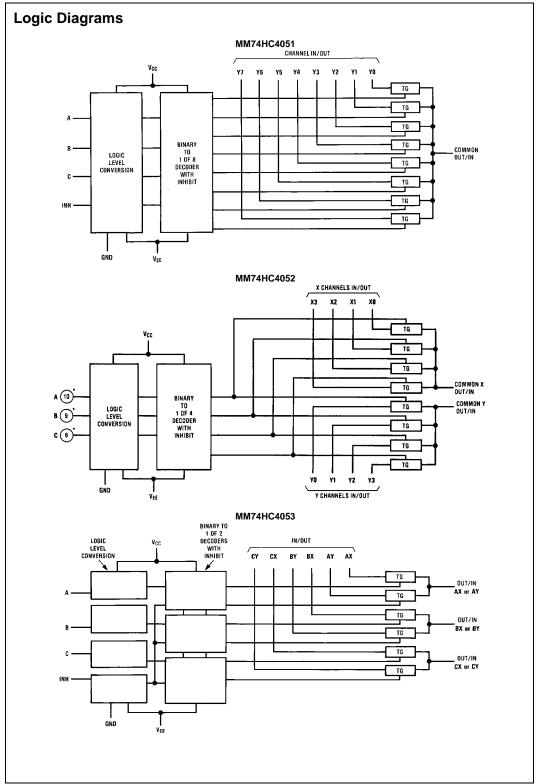
	Inp	ut		"ON"
Inh	С	В	Α	Channel
Н	Х	Χ	Χ	None
L	L	L	L	Y0
L	L	L	Н	Y1
L	L	Н	L	Y2
L	L	Н	Н	Y3
L	Н	L	L	Y4
L	Н	L	Н	Y5
L	Н	Н	L	Y6
L	Н	Н	Н	Y7

### MM744052

In	puts		"ON" Channels				
Inh	В	Α	Х	Υ			
Н	Х	Χ	None	None			
L	L	L	0X	0Y			
L	L	Н	1X	1Y			
L	Н	L	2X	2Y			
L	Н	Н	3X	3Y			

### MM744053

	Inp	ut		"ON	" Channels			
Inh	С	В	Α	C	b	а		
Н	Х	Χ	Χ	None	None	None		
L	L	L	L	CX	ВХ	AX		
L	L	L	Н	CX	вх	AY		
L	L	Н	L	CX	BY	AX		
L	L	Н	Н	CX	BY	AY		
L	Н	L	L	CY	вх	AX		
L	Н	L	Н	CY	вх	AY		
L	Н	Н	L	CY	BY	AX		
L	Н	Н	Н	CY	BY	AY		



#### **Absolute Maximum Ratings**(Note 1) (Note 2) Supply Voltage (V<sub>CC</sub>) -0.5 to +7.5V Supply Voltage (V<sub>EE</sub>) +0.5 to -7.5V Control Input Voltage (V<sub>IN</sub>) -1.5 to $V_{CC} + 1.5V$ Switch I/O Voltage (V<sub>IO</sub>) $V_{\text{EE}}$ -0.5 to $V_{\text{CC}}$ +0.5V Clamp Diode Current (I<sub>IK</sub>, I<sub>OK</sub>) ±20 mA Output Current, per pin (I<sub>OUT</sub>) ±25 mA V<sub>CC</sub> or GND Current, per pin (I<sub>CC</sub>) ±50 mA Storage Temperature Range (T<sub>STG</sub>) $-65^{\circ}C$ to $+150^{\circ}C$ Power Dissipation (P<sub>D</sub>) (Note 3) 600 mW S.O. Package only 500 mW Lead Temperature (T<sub>L</sub>) (Soldering 10 seconds) 260°C

# Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )	2	6	V
Supply Voltage (V <sub>EE</sub> )	0	-6	V
DC Input or Output Voltage			
$(V_{IN}, V_{OUT})$	0	$V_{CC}$	V
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

**Note 1:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: –

12 mW/°C from 65°C to 85°C.

## DC Electrical Characteristics (Note 4)

Symbol	Parameter		Conditions V <sub>F</sub>	V <sub>FF</sub>	V <sub>CC</sub>	T <sub>A</sub> =	25°C	$T_A = -40 \text{ to } 85^{\circ}\text{C}$	$T_A = -55$ to $125^{\circ}C$	Units
Symbol	Farameter		Conditions	, FE		Тур		Guaranteed I	imits	Omis
V <sub>IH</sub>	Minimum HIGH Level				2.0V		1.5	1.5	1.5	V
	Input Voltage				4.5V		3.15	3.15	3.15	V
					6.0V		4.2	4.2	4.2	V
$V_{IL}$	Maximum LOW Level				2.0V		0.5	0.5	0.5	V
	Input Voltage				4.5V		1.35	1.35	1.35	V
					6.0V		1.8	1.8	1.8	V
R <sub>ON</sub>	Maximum "ON" Resista	nce	$V_{INH} = V_{IL}, I_{S} = 2.0 \text{ mA}$	GND	4.5V	40	160	200	240	Ω
	(Note 5)		$V_{IS} = V_{CC}$ to $V_{EE}$	-4.5V	4.5V	30	120	150	170	Ω
			(Figure 1)	-6.0V	6.0V	20	100	125	140	Ω
			$V_{INH} = V_{IL}, I_{S} = 2.0 \text{ mA}$	GND	2.0V	100	230	280	320	Ω
			$V_{IS} = V_{CC}$ or $V_{EE}$	GND	4.5V	40	110	140	170	Ω
			(Figure 1)	-4.5V	4.5V	20	90	120	140	Ω
				-6.0V	6.0V	15	80	100	115	Ω
R <sub>ON</sub>	Maximum "ON" Resista	nce	$V_{CTL} = V_{IL}$	GND	4.5V	10	20	25	25	Ω
	Matching		$V_{IS} = V_{CC}$ to GND	-4.5V	4.5V	5	10	15	15	Ω
				-6.0V	6.0V	5	10	12	15	Ω
I <sub>IN</sub>	Maximum Control		V <sub>IN</sub> = V <sub>CC</sub> or GND				±0.1	±1.0	±1.0	μΑ
	Input Current		$V_{CC} = 2-6V$							
I <sub>CC</sub>	Maximum Quiescent		$V_{IN} = V_{CC}$ or GND	GND	6.0V		8	80	160	μΑ
	Supply Current		$I_{OUT} = 0 \mu A$	-6.0V	6.0V		16	160	320	μΑ
$I_{IZ}$	Maximum Switch "OFF"	,	V <sub>OS</sub> = V <sub>CC</sub> or V <sub>EE</sub>	GND	6.0V		±60	±600	±600	nA
	Leakage Current		$V_{IS} = V_{EE} or V_{CC}$	-6.0V	6.0V		±100	±1000	±1000	nA
	(Switch Input)		V <sub>INH</sub> = V <sub>IH</sub> (Figure 2)							
$I_{IZ}$	Maximum Switch		$V_{IS} = V_{CC}$ to $V_{EE}$	GND	6.0V		±0.2	±2.0	±2.0	μΑ
	"ON" Leakage	HC4051	$V_{INH} = V_{IL}$	-6.0V	6.0V		±0.4	±4.0	±4.0	μΑ
	Current		(Figure 3)							
			$V_{IS} = V_{CC}$ to $V_{EE}$	GND	6.0V		±0.1	±1.0	±1.0	μΑ
		HC4052	V <sub>INH</sub> = V <sub>IL</sub> (Figure 3)	-6.0V	6.0V		±0.2	±2.0	±2.0	μΑ
			$V_{IS} = V_{CC}$ to $V_{EE}$	GND	6.0V		±0.1	±1.0	±1.0	μΑ
		HC4053	V <sub>INH</sub> = V <sub>IL</sub> (Figure 3)	-6.0V	6.0V		±0.1	±1.0	±1.0	μΑ

## DC Electrical Characteristics (Continued)

Symbol	Parameter		Conditions	VEE	v <sub>cc</sub>	$T_A = 25^{\circ}C$		$T_A = -40 \text{ to } 85^{\circ}\text{C}$	T <sub>A</sub> = -55 to 125°C	Units
Cymbol	. a.a.iieto		J Soliditions	- 55	- 66	Тур		Guaranteed I		
I <sub>IZ</sub>	Maximum Switch		$V_{OS} = V_{CC}$ or $V_{EE}$	GND	6.0V		±0.2	±2.0	±2.0	μΑ
	"OFF" Leakage	HC4051	$V_{IS} = V_{EE}$ or $V_{CC}$	-6.0V	6.0V		±0.4	±4.0	±4.0	μΑ
	Current (Common Pin)		$V_{INH} = V_{IH}$							
			$V_{OS} = V_{CC}$ or $V_{EE}$	GND	6.0V		±0.1	±1.0	±1.0	μΑ
		HC4052	$V_{IS} = V_{EE}$ or $V_{CC}$	-6.0V	6.0V		±0.2	±2.0	±2.0	μΑ
			$V_{INH} = V_{IH}$							
			$V_{OS} = V_{CC}$ or $V_{EE}$	GND	6.0V		±0.1	±1.0	±1.0	μΑ
		HC4053	$V_{IS} = V_{EE}$ or $V_{CC}$	-6.0V	6.0V		±0.1	±1.0	±1.0	μΑ
			$V_{INH} = V_{IH}$							

Note 4: For a power supply of 5V  $\pm$ 10% the worst case on resistances (R<sub>ON</sub>) occurs for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub> = 5.5V and 4.5V respectively. (The V<sub>IH</sub> value at 5.5V is 3.85V.) The worst case leakage current occur for CMOS at the higher voltage and so the 5.5V values should be used.

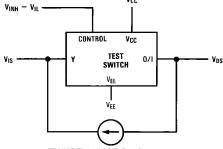
Note 5: At supply voltages (V<sub>CC</sub>-V<sub>EE</sub>) approaching 2V the analog switch on resistance becomes extremely non-linear. Therefore it is recommended that these devices be used to transmit digital only when using these supply voltages.

### **AC Electrical Characteristics**

 $V_{CC}$  = 2.0V–6.0V,  $V_{EE}$  = 0V–6V,  $C_L$  = 50 pF (unless otherwise specified)

Symbol   Parameter   Conditions   Vee   Vcc   Typ   Guaranteed Literal Lite	T <sub>A</sub> = -55 to 125°C	Units
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	imits	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	90	ns
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	18	ns
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	14	ns
"ON" Delay	13	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	515	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	103	ns
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	69	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	62	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	435	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	87	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	56	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	48	ns
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	N	MHz
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	N	MHz
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	,	mV
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$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		dB
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		dB
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		dB
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$		dB
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		%
f = 1 kHz         5         10         10           C <sub>IN</sub> Maximum Control         5         10         10		%
	10	pF
Input Capacitance		
C <sub>IN</sub> Maximum Switch Input 15		pF
Input Capacitance 4051 Common 90		
4052 Common 45		
4053 Common 30		
C <sub>IN</sub> Maximum Feedthrough 5 Capacitance		pF
CORPORTION	<u> </u>	

# **AC Test Circuits and Switching Time Waveforms**



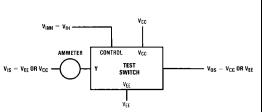


FIGURE 1. "ON" Resistance

FIGURE 2. "OFF" Channel Leakage Current

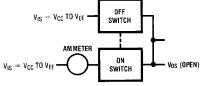
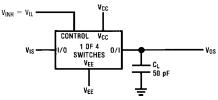


FIGURE 3. "ON" Channel Leakage Current



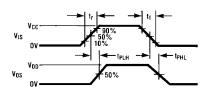
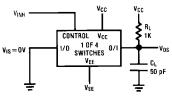
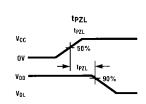


FIGURE 4.  $t_{\text{PHL}}$ ,  $t_{\text{PLH}}$  Propagation Delay Time Signal Input to Signal Output





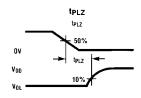
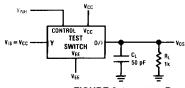
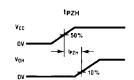


FIGURE 5.  $t_{\text{PZL}}$ ,  $t_{\text{PLZ}}$  Propagation Delay Time Control to Signal Output





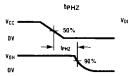


FIGURE 6.  $t_{\text{PZH}}$ ,  $t_{\text{PHZ}}$  Propagation Delay Time Control to Signal Output

# AC Test Circuits and Switching Time Waveforms (Continued)

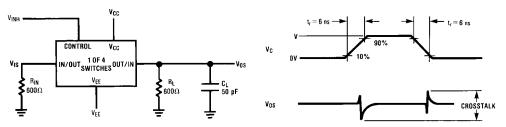


FIGURE 7. Crosstalk: Control Input to Signal Output

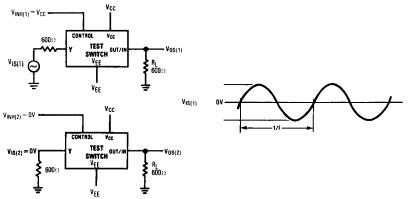
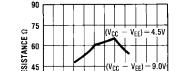
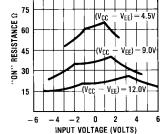


FIGURE 8. Crosstalk Between Any Two Switches

# **Typical Performance Characteristics**



Typical "On" Resistance vs Input Voltage

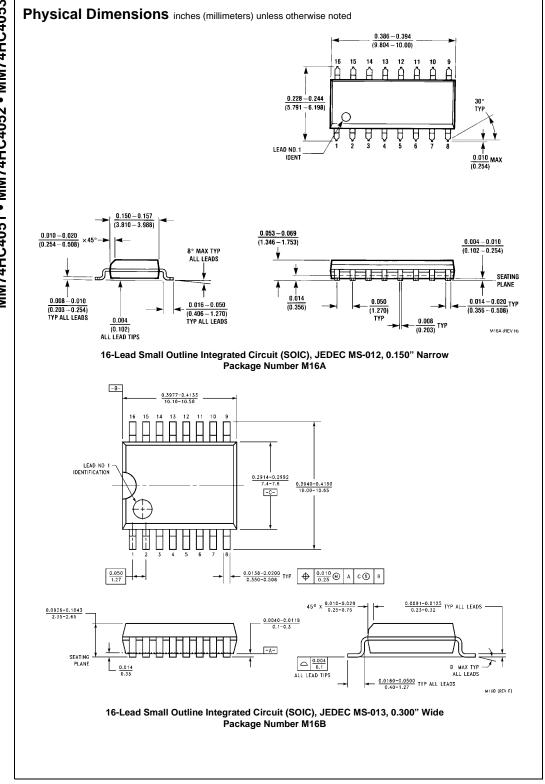


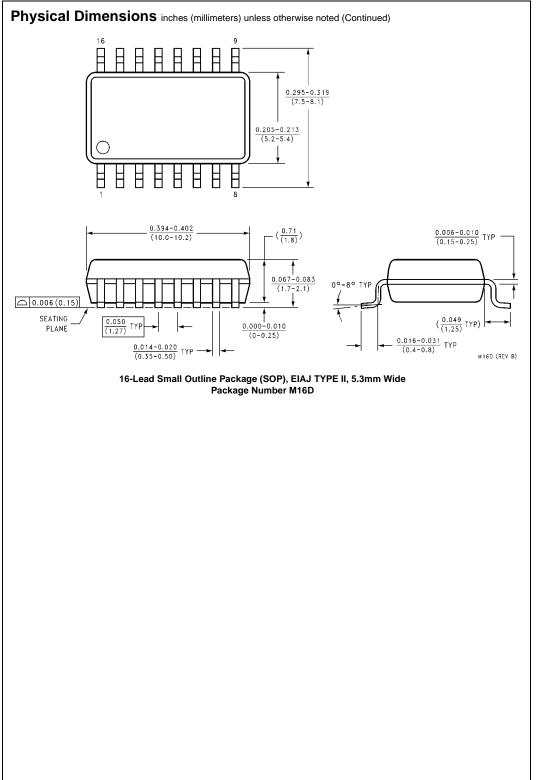
 $\mathbf{V_{CC}} {=} {-} \mathbf{V_{EE}}$ 

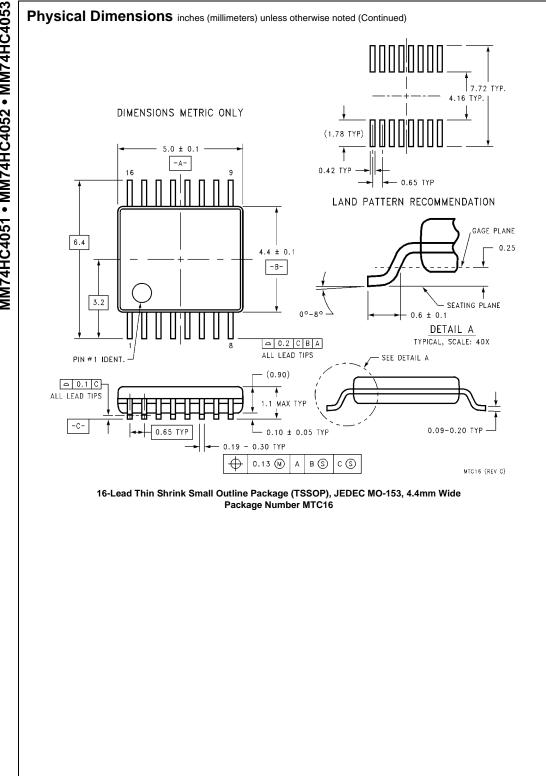
### **Special Considerations**

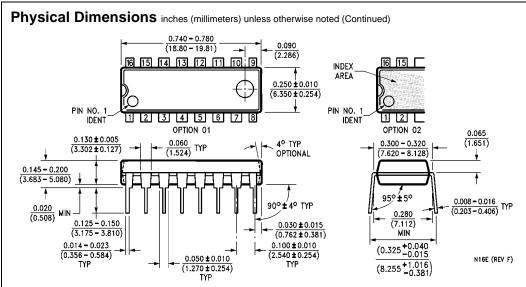
In certain applications the external load-resistor current may include both  $V_{\mbox{\scriptsize CC}}$  and signal line components. To

avoid drawing  $\mathbf{V}_{\mathbf{CC}}$  current when switch current flows into the analog switch pins, the voltage drop across the switch must not exceed 1.2V (calculated from the ON resistance).









16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N16E

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